

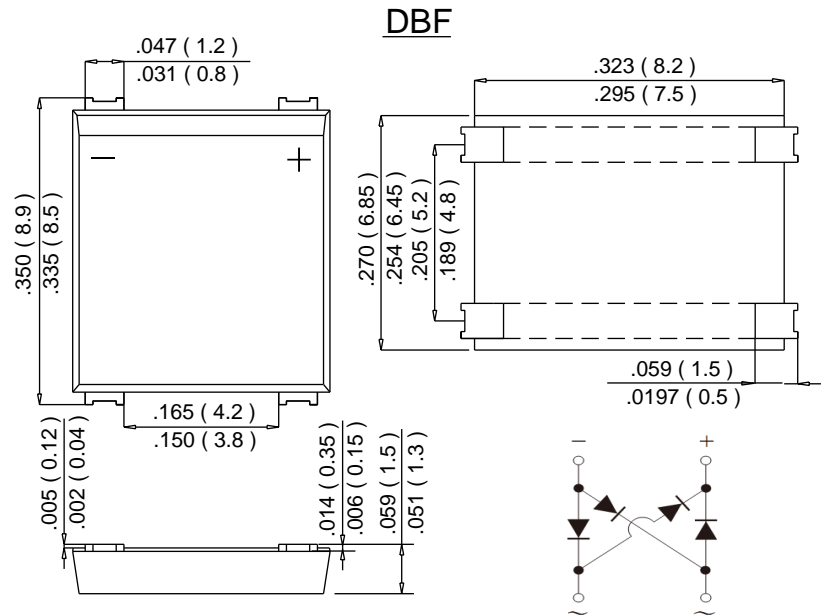
SINGLE PHASE 3.0AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-110A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case: DBF, molded plastic
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	DBF302S	DBF303S	DBF304S	DBF305S	DBF306S	DBF307S	UNITS
Peak Repetitive Reverse Voltage	V_{RRM}							
Working Peak Reverse Voltage	V_{RWM}	100	200	400	600	800	1000	V
DC Blocking Voltage	V_{DC}							
RMS Reverse Voltage	V_{RMS}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@ $T_C=100^\circ C$	IF(AV)	3.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	110						A
I^2t Rating for Fusing ($t < 8.3ms$)	I^2t	50.215						A ² s
Forward Voltage per element @IF=1.5A @IF=3.0A	V_{FM}	0.95 1.0						V
Peak Reverse Current @ $T_J=25^\circ C$ At Rated DC Blocking Voltage @ $T_J=125^\circ C$	I_R	5.0 100						μA
Typical Junction Capacitance (Note 2)	C_J	30						pF
Typical Thermal Resistance (Note 3)	$R_{\theta JA}$	15						$^\circ C/W$
	$R_{\theta JC}$	5						
Operating and Storage Temperature Range	T_J, T_{STG}	-55to+150						$^\circ C$

Note: 1. Mounted on glass epoxy PC board with 1.3mm solder pad.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

3. Mounted on 15 mm*12 mm*1.6mmAL pad attach 195 mm*110 mm*10 mm steel plate

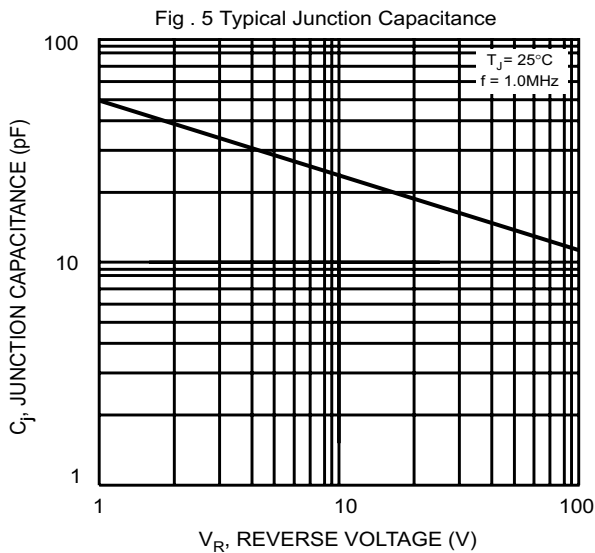
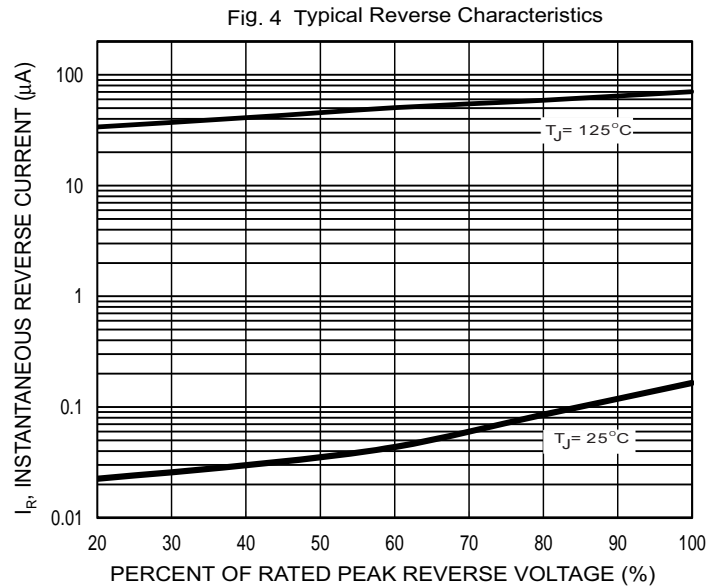
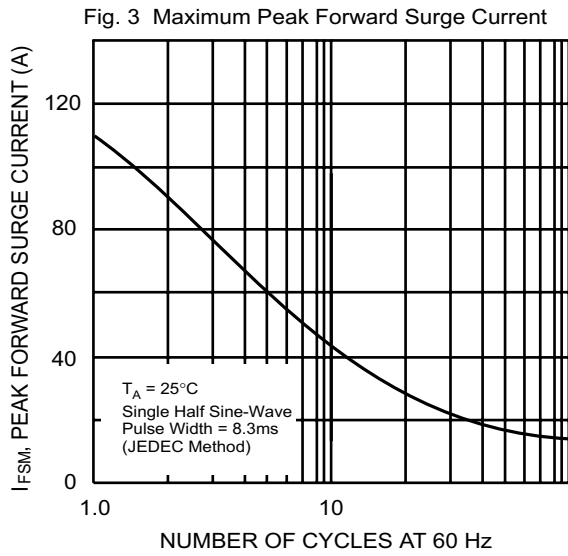
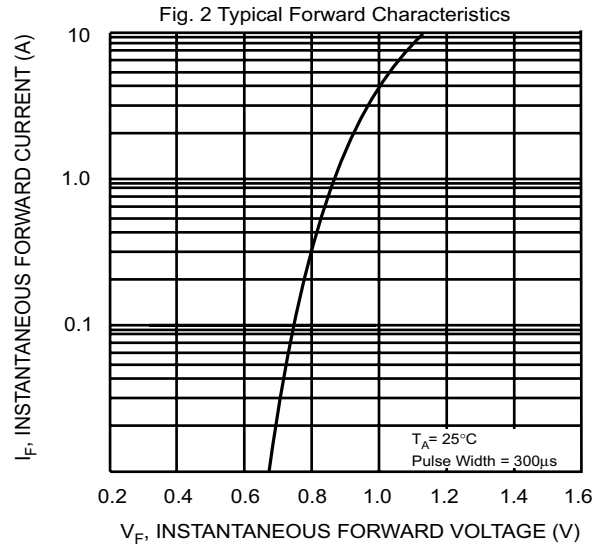
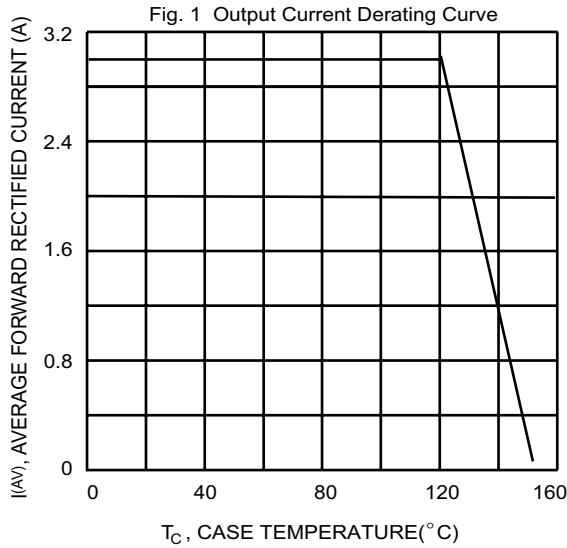


FIG.6 MOUNTING PAD LAYOUT

